SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

- **Short-Circuit Protection**
- **Wide Common-Mode and Differential Voltage Ranges**
- **No Frequency Compensation Required**
- **Low Power Consumption**
- No Latch-Up
- Designed to Be Interchangeable With Motorola MC1558/MC1458 and Signetics S5558/N5558

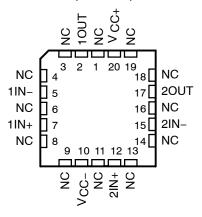
description/ordering information

MC1458 and MC1558 are general-purpose operational amplifiers, with each half electrically similar to the µA741, except that offset null capability is not provided.

The high-common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.

MC1458 . . . D, P, OR PS PACKAGE MC1558 . . . JG PACKAGE (TOP VIEW) **10UT** 8 | V_{CC}+ 1IN-7 1 20UT 1IN+ 6 **∏** 2IN− 3 5 1 2IN+ V_{CC} -

MC1558 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

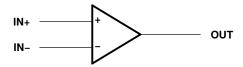
T _A	V _{IO} max AT 25°C	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PDIP (P)	Tube	MC1458P	MC1458P
0°C to 70°C	6 mV	0010 (D)	Tube	MC1458D	1404450
		SOIC (D)	Tape and reel	MC1458DR	MC1458
		SOP (PS)	Tape and reel	MC1458PSR	M1458
		CDIP (JG)	Tube	MC1558JG	MC1558JG
−55°C to 125°C	5 mV	CDIP (JGB)	Tube	MC1558JGB	MC1558JGB
		LCCC (FK)	Tube	MC1558FK	MC1558FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

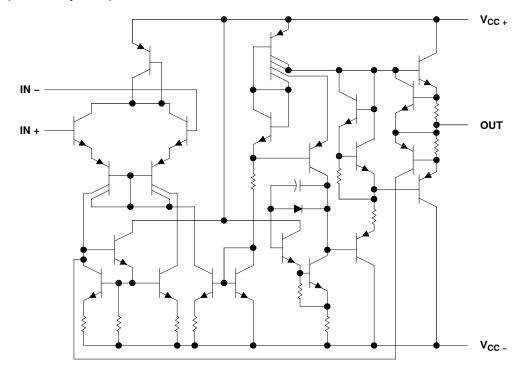
POST OFFICE BOX 655.33 • DALLAS, 1.2XA 7.26.
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

symbol (each amplifier)



schematic (each amplifier)



SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - 4. The output can be shorted to ground or either power supply. For the MC1558 only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 70°C free-air temperature.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

			MIN	MAX	UNIT
V _{CC±}	Supply voltage		±5	±15	V
т.	Operating free air temperature range	MC1458	0	70	°C
IA	Operating free-air temperature range	MC1558	-55	125	C

SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

electrical characteristics at specified free-air temperature, $V_{\text{CC}\pm}$ = $\pm 15~\text{V}$

DARAMETER		TEGT 0011DITIO	N	/IC1458		MC1558				
	PARAMETER	TEST CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
\/	land offeet velters	V 0	25°C		1	6		1	5	\/
V _{IO}	Input offset voltage	V _O = 0	Full range			7.5			6	mV
	land offeet everent	V 0	25°C		20	200		20	200	~^
I _{IO}	Input offset current	V _O = 0	Full range			300			500	nA
	logest bigg accurant	V 0	25°C		80	500		80	500	~^
I _{IB}	Input bias current	V _O = 0	Full range			800			1500	nA
V	Common-mode input		25°C	±12	±13		±12	±13		V
V _{ICR}	voltage range		Full range	±12			±12			V
		$R_L = 10 \text{ k}\Omega$	25°C	±12	±14		±12	±14		
	Maximum peak output	$R_L \ge 10 \text{ k}\Omega$	Full range	±12			±11			V
V_{OM}	voltage swing	$R_L = 2 k\Omega$	25°C	±10	±13		±10	±13		V
		$R_L \ge 2 k\Omega$	Full range	±10			±10			
	Large-signal differential	D . 010	25°C	20	200		50	200		.,, .,
A_{VD}	voltage amplification	$R_L \ge 2 k\Omega$, $V_O = \pm 10 V$	Full range	15			25			V/mV
B _{OM}	Maximum-output-swing bandwidth (closed loop)	$\begin{aligned} R_L &= 2 \text{ k}\Omega, & V_O \geq \pm 10 \text{ V}, \\ A_{VD} &= 1, & THD \geq 5\% \end{aligned}$	25°C		14			14		kHz
B ₁	Unity-gain bandwidth		25°C		1			1		MHz
фm	Phase margin	A _{VD} = 1	25°C		65			65		deg
	Gain margin		25°C		11			11		dB
r _i	Input resistance		25°C	0.3	2		0.3*	2		MΩ
r _o	Output resistance	V _O = 0, See Note 9	25°C		75			75		Ω
C _i	Input capacitance		25°C		1.4			1.4		pF
z _{ic}	Common-mode input impedance	f = 20 Hz	25°C		200			200		МΩ
OMBB	Common-mode	V _{IC} = V _{ICR} min,	25°C	70	90		70	90		
CMRR	rejection ratio	V _O = 0	Full range	70			70			dB
1-	Supply-voltage sensitivity	$V_{CC} = \pm 9 \text{ V to } \pm 15 \text{ V},$	25°C		30	150		30	150	
k _{SVS}	$(\Delta V_{IO}/\Delta V_{CC})$	V _O = 0	Full range			150			150	μ V/V
V _n	Equivalent input noise voltage (closed loop)	$A_{VD} = 100, \qquad R_{S} = 0, \\ f = 1 \text{ kHz}, \qquad BW = 1 \text{ Hz}$	25°C		45			45		nV/√ Hz
I _{OS}	Short-circuit output current		25°C		±25	±40		±25	±40	mA
loo	Supply current	$V_O = 0$, No load	25°C		3.4	5.6		3.4	5	mA
I _{CC}	(both amplifiers)	VO - U, NU luau	Full range			6.6			6.6	IIIA
P_{D}	Total power dissipation	$V_{O} = 0$, No load	25°C		100	170		100	150	mW
ı-D	(both amplifiers)	VO = 0, INO IOau	Full range			200			200	
V_{O1}/V_{O2}	Crosstalk attenuation		25°C		120			120		dB

^{*}On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All characteristics are specified under open-loop operating conditions with zero common-mode input voltage, unless otherwise specified. Full range for MC1458 is 0°C to 70°C and for MC1558 is – 55°C to 125°C.

NOTE 9: This typical value applies only at frequencies above a few hundred hertz because of the effect of drift and thermal feedback.

SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

operating characteristics, $V_{CC\pm}$ = ±15 V, C_L = 100 pF, T_A = 25°C (see Figure 1)

PARAMETER		TEOT 001	TECT CONDITIONS				MC1558			
		TEST CO	TEST CONDITIONS			MAX	MIN	TYP	MAX	UNIT
T	Rise time	V _I = 20 mV,	$R_L = 2 k\Omega$,		0.3			0.3		μs
τ _r	Overshoot factor	V _I = 20 mV,	$R_L = 2 k\Omega$		5			5		%
SR	Slew rate at unity gain	V _I = 10 V,	$R_L = 2 k\Omega$		0.5			0.5		V/μs

PARAMETER MEASUREMENT INFORMATION

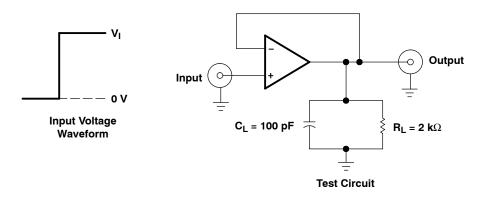


Figure 1. Rise-Time, Overshoot, and Slew-Rate Waveform and Test Circuit



PACKAGE OPTION ADDENDUM



31-Jul-2010

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9760301Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
5962-9760301QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	Purchase Samples
MC1458D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
MC1458P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
MC1458PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
MC1458PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
MC1458PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
MC1458PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
MC1558FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
MC1558JG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	Purchase Samples
MC1558JGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	Purchase Samples
MC1558P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	Samples Not Available
SN98212P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



PACKAGE OPTION ADDENDUM



www.ti.com 31-Jul-2010

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF MC1558, MC1558M:

Catalog: MC1558

Military: MC1558M

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

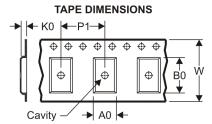


PACKAGE MATERIALS INFORMATION

www.ti.com 8-Jul-2011

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Ī	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ŀ	MC1458DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
I	MC1458PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1



www.ti.com 8-Jul-2011

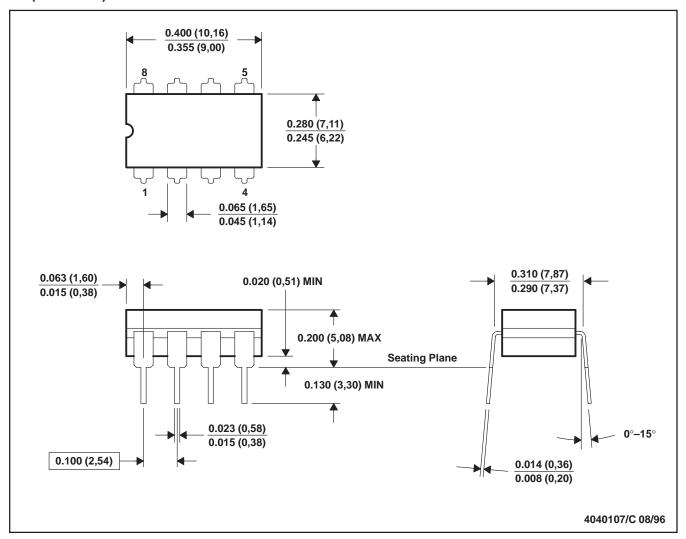


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MC1458DR	SOIC	D	8	2500	346.0	346.0	29.0
MC1458PSR	SO	PS	8	2000	346.0	346.0	33.0

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



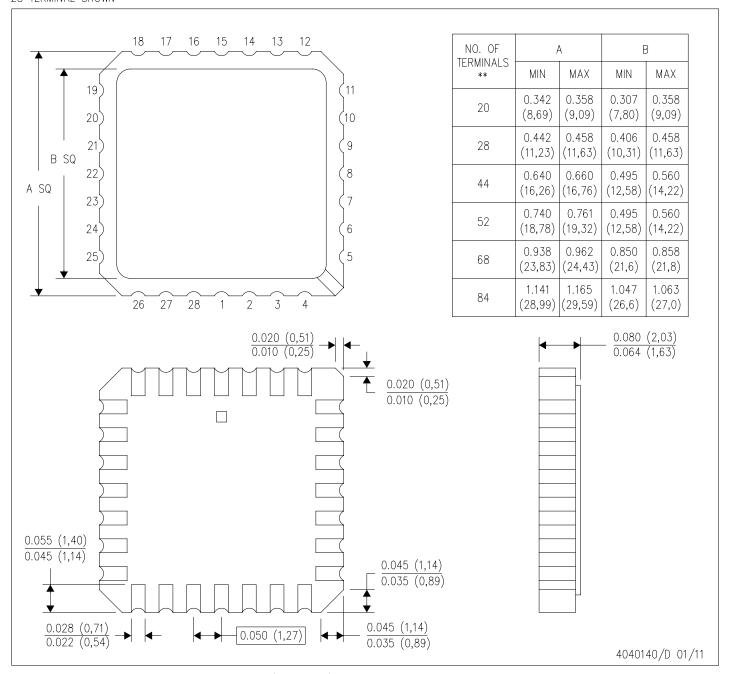
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

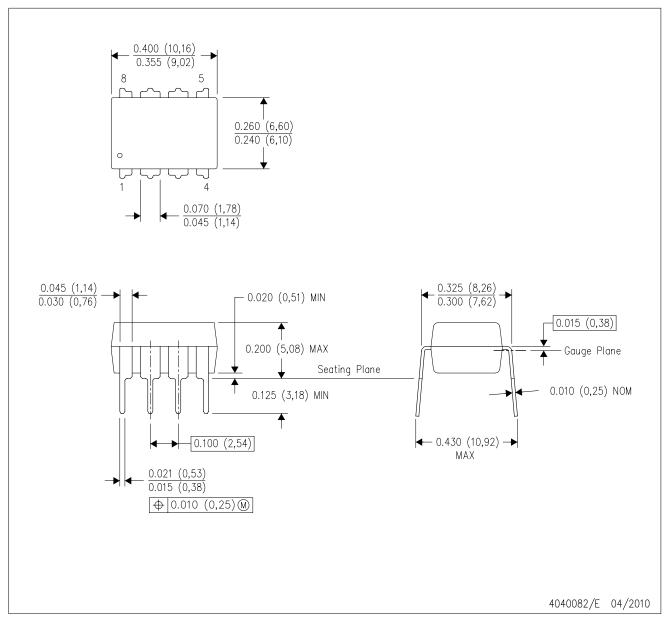
28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

P (R-PDIP-T8)

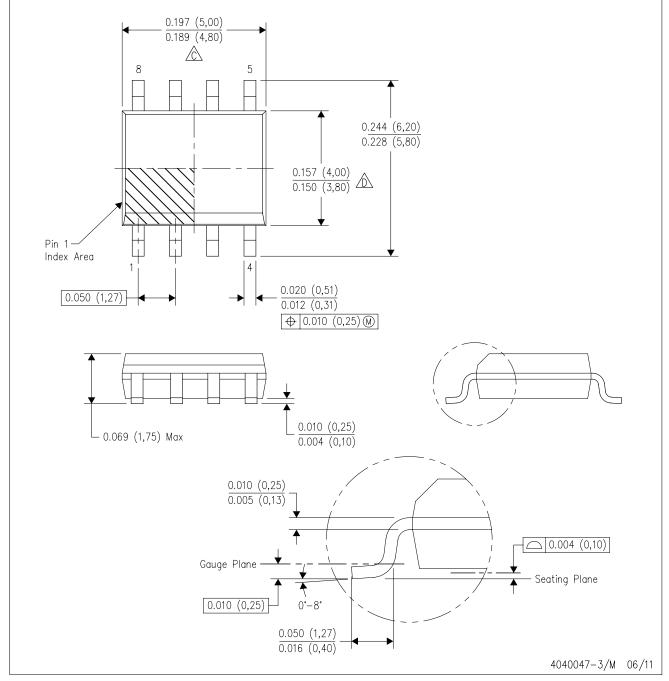
PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

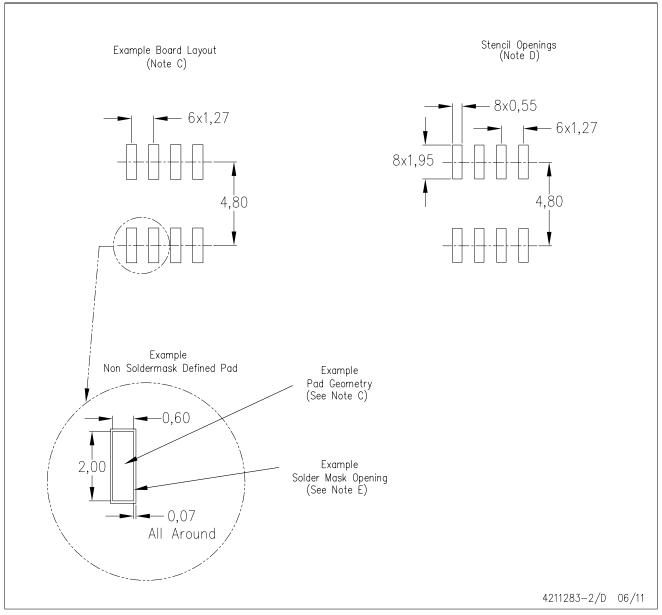


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

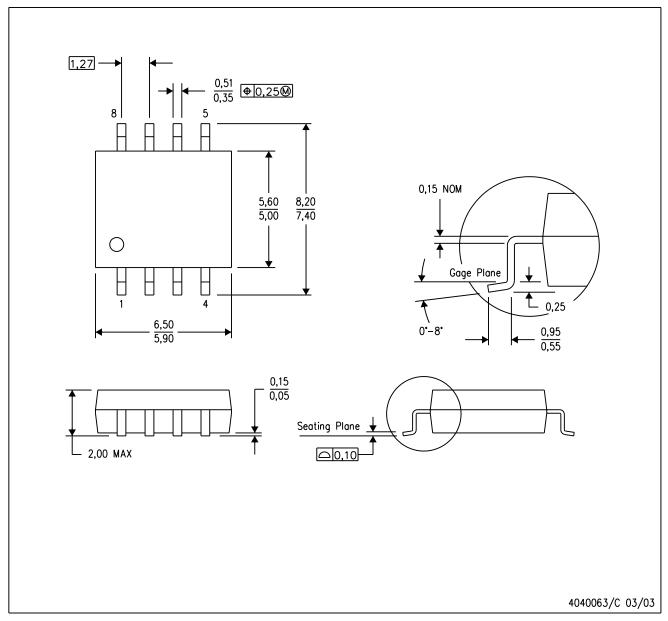


D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

Applications

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

RF/IF and ZigBee® Solutions www.ti.com/lprf

Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
DSP	dsp.ti.com	Industrial	www.ti.com/industrial
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Security	www.ti.com/security
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Power Mgmt	<u>power.ti.com</u>	Transportation and Automotive	www.ti.com/automotive
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps

TI E2E Community Home Page <u>e2e.ti.com</u>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated

